

B' The invention solves the foregoing problem of trace interposition by providing an electrically-conductive bridge 90 to span in an overhead manner across the interposing electrically-conductive trace 70A, and then electrically connecting one end of the electrically-conductive bridge 90 by means of a first trace 70' to the bond finger 60B and the other end of the same by means of a second trace 70" to the via 80A (note that if the first end of the electrically-conductive bridge 90 is directly bonded to the bond finger 60B, the first trace 70' can be eliminated; and if the second end of the electrically-conductive bridge 90 is directly bonded to the via 80A, the second trace 70" can be eliminated).

IN THE CLAIMS

Please **amend** claims 6, 11, and 13 as follows:

- B2
6. (Amended) A BGA (ball grid array) package, which comprises:
- (a) a substrate having a front side and a back side;
 - (b) a semiconductor chip mounted on the front side of the substrate, the semiconductor chip having an array of bond pads;
 - (c) an array of solder balls implanted on the back side of the substrate;
 - (d) an array of bond fingers provided beside the semiconductor chip and which are electrically connected to the bond pads on the semiconductor chip;
 - (e) an array of electrically-conductive vias, each penetrating from the front side to the back side of the substrate and electrically connected to one of the solder balls;
 - (f) a plurality of continuous electrically-conductive traces for electrically connecting a first subgroup of the bond fingers to corresponding ones of the vias, these continuous electrically-conductive traces including at least one being interposed between a second subgroup of the bond fingers and their corresponding vias; and
 - (g) an electrically-conductive bridge as a bonding wire that spans in an overhead manner across the interposing electrically-conductive trace such that the bonding wire is free of interference with the interposing electrically-conductive trace and a gap is formed between the bonding wire and the interposing electrically-conductive trace, wherein the bonding wire has one

B2 end electrically connected to the corresponding via and the other end electrically connected to the corresponding bond finger.

11. (Amended) A BGA (ball grid array) package, which comprises:

- B3
- (a) a substrate having a front side and a back side;
 - (b) a semiconductor chip mounted on the front side of the substrate, the semiconductor chip having an array of bond pads;
 - (c) an array of solder balls implanted on the back side of the substrate;
 - (d) an array of bond fingers provided beside the semiconductor chip and which are electrically connected to the bond pads on the semiconductor chip;
 - (e) an array of electrically-conductive vias, each penetrating from the front side to the back side of the substrate and electrically connected to one of the solder balls;
 - (f) a plurality of continuous electrically-conductive traces for electrically connecting a first subgroup of the bond fingers to corresponding ones of the vias, these continuous electrically-conductive traces including at least one being interposed between a second subgroup of the bond fingers and their corresponding vias; and
 - (g) an electrically-conductive bridge as a chip resistor that spans in an overhead manner across the interposing electrically-conductive trace such that the chip resistor is free of interference with the interposing electrically-conductive trace and a gap is formed between the chip resistor and the interposing electrically-conductive trace, wherein the chip resistor has one end electrically connected to the corresponding via and the other end electrically connected to the corresponding bond finger.
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B4 13. (Amended) The BGA package of claim 11, wherein the chip resistor is a zero-resistance chip resistor.

Please **cancel** claims 1-5 without prejudice.